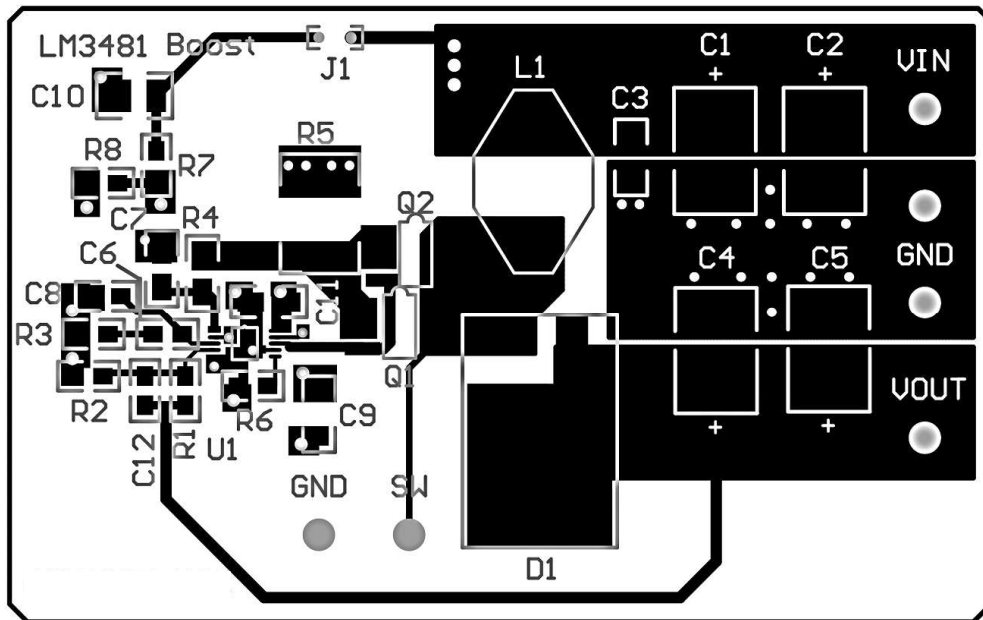
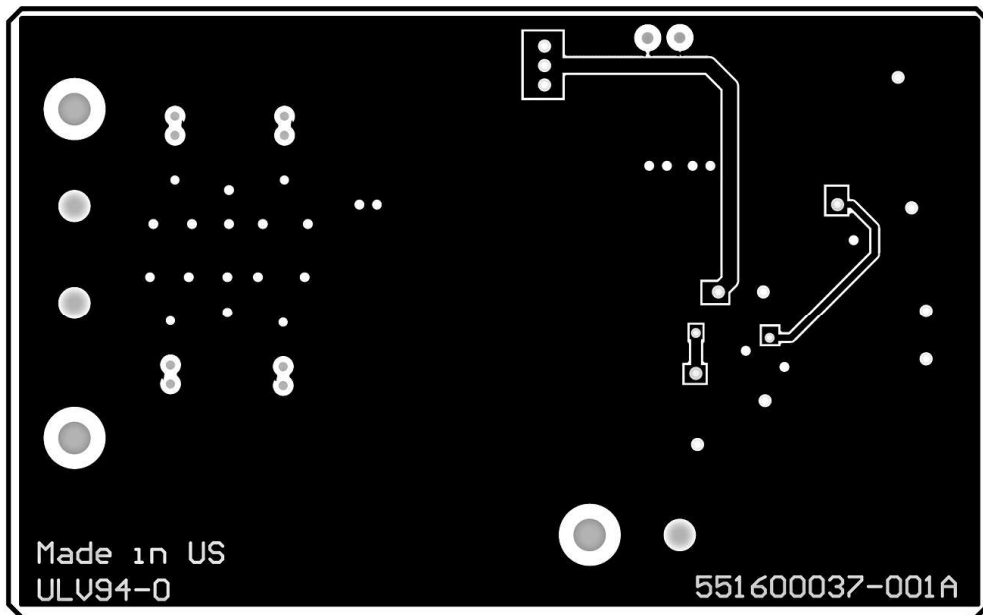


PMP11784 Rev.B

Top Layer + Assembly



Bottom Layer + Assembly



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